

N-Channel Depletion-Mode DMOS FET

Features

- Free from secondary breakdown
- Low power drive requirement
- Ease of paralleling
- Excellent thermal stability
- Integral source-drain diode
- High input impedance and low C_{ISS}
- ESD gate protection

General Description

The LND250 is a high voltage N-channel depletion mode (normally-on) transistor utilizing Supertex's lateral DMOS technology. The gate is ESD protected.

The LND250 is ideal for high voltage applications in the areas of normally-on switches, precision constant current sources, voltage ramp generation and amplification.

- Applications
 - Solid state relays
 - Normally-on switches
 - Converters
 - Power supply circuits
 - Constant current sources
 - Input protection circuits

Ordering Information

Part Number	Package Options	Packing		
LND250K1-G*	TO-236AB (SOT-23)	3000/Reel		

-G denotes a lead (Pb)-free / RoHS compliant package

Part is not recommended for new designs. Please refer to LND150K1-G.

Absolute Maximum Ratings

Parameter	Value
Drain-to-source	BV _{DSX}
Drain-to-gate	BV _{DGX}
Gate-to-source	±20V
Operating and storage temperature	-55°C to +150°C

Absolute Maximum Ratings are those values beyond which damage to the device may occur. Functional operation under these conditions is not implied. Continuous operation of the device at the absolute rating level may affect device reliability. All voltages are referenced to device ground.

Product Summary

BV _{DSX} /BV _{DGX} (V)	R _{DS(ON)} (max)	l _{DSS} (min)
500	1.0kΩ	1.0mA

Pin Configuration



Product Marking

NDEW

W = Code for Week Sealed — = "Green" Packaging

TO-236AB (SOT-23)

Packages may or may not include the following marks: Si or



LND250

Thermal Characteristics

Package	I _D (continuous) [†] (mA)	I _D (pulsed) (mA)	Power Dissipation @T _A = 25°C (W)	θ _{ja} (°C/W)	l _{DR} (mA)	l _{DRM} † (mA)
TO-236AB (SOT-23)	13	30	0.36	203	13	30

Notes:

† I_{D} (continuous) is limited by max rated T_{j} .

Electrical Characteristics (*T_A* = 25°C unless otherwise specified)

Sym	Parameter		Тур	Max	Units	Conditions			
BV _{DSX}	Drain-to-source breakdown voltage	500	-	-	V	V _{GS} = -10V, I _D = 1.0mA			
V _{GS(OFF)}	Gate-to-source off voltage	-1.0	-	-3.0	V	V _{GS} = 25V, I _D = 100nA			
$\Delta V_{\text{GS(OFF)}}$	Change in $V_{GS(OFF)}$ with temperature	-	-	5.0	mV/ºC	V _{GS} = 25V, I _D = 100nA			
I _{GSS}	Gate body leakage current	-	-	100	nA	V_{GS} = ± 20V, V_{DS} = 0V			
		-	-	100	nA	V _{GS} = -10V, V _{DS} = 450V			
I _{D(OFF)}	Drain-to-source leakage current	-	-	100	μA	$V_{DS} = 0.8V$ Max Rating, $V_{GS} = -10V$, $T_A = 125^{\circ}C$			
I _{DSS}	Saturated drain-to-source current		-	3.0	mA	$V_{_{ m GS}}$ = 0V, $V_{_{ m DS}}$ = 25V			
R _{DS(ON)}	Static drain-to-source on-state resistance	-	850	1000	Ω	$V_{_{\rm GS}}$ = 0V, I _D = 0.5mA			
$\Delta R_{DS(ON)}$	Change in $R_{DS(ON)}$ with temperature	-	-	1.2	%/°C	$V_{_{\rm GS}}$ = 0V, I_{_{\rm D}} = 0.5mA			
G _{FS}	Forward transductance	1.0	2.0	-	mmho	$V_{\rm DS} = 0V, I_{\rm D} = 1.0 {\rm mA}$			
C _{ISS}	Input capacitance	-	7.5	10		V _{GS} = -10V, V _{DS} = 25V,			
C _{oss}	Common source output capacitance	-	2.0	3.5	pF				
C _{RSS}	Reverse transfer capacitance	-	0.5	1.0		f = 1.0MHz			
t _{d(ON)}	Turn-on delay time	-	0.09	-					
t _r	Rise time	-	0.45	-		$V_{DD} = 25V,$ $I_{D} = 1.0mA,$ $R_{GEN} = 25\Omega$			
t _{d(OFF)}	Turn-off delay time	-	0.1	-	μs				
t _r	Fall time	-	1.3	-					
V _{SD}	Diode forward voltage drop	-	-	0.9	V	V _{GS} = -10V, I _{SD} = 1.0mA			
t _{rr}	Reverse recovery time	-	200	-	ns	V _{GS} = -10V, I _{SD} = 1.0mA			

Notes:

1. All D.C. parameters 100% tested at 25°C unless otherwise stated. (Pulse test: 300µs pulse, 2% duty cycle.)

2. All A.C. parameters sample tested.

Switching Waveforms and Test Circuit



3-Lead TO-236AB (SOT-23) Package Outline (K1)

2.90x1.30mm body, 1.12mm height (max), 1.90mm pitch



View A - A

Symb	ol	Α	A1	A2	b	D	E	E1	е	e1	L	L1	θ	
Dimension (mm)	MIN	0.89	0.01	0.88	0.30	2.80	2.10	1.20			4.00	0.20†		0 0
	NOM	-	-	0.95	-	2.90	-	1.30	0.95 BSC		0.50	0.54 REF	-	
	MAX	1.12	0.10	1.02	0.50	3.04	2.64	1.40	000		000	0.60		8 0

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JEDEC Registration TO-236, Variation AB, Issue H, Jan. 1999.

Side View

† This dimension differs from the JEDEC drawing.

Drawings not to scale.

↑A1

Supertex Doc.#: DSPD-3TO236ABK1, Version C041309.

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information go to <u>http://www.supertex.com/packaging.html</u>.)

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